

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|--|----------|------------------|---------|------------------|
| L1 | 3 | ((ultra adj fine) nano) with particles with (planarize planarized planarizes planarizing).clm. | US-PGPUB | OR | OFF | 2005/08/03 09:58 |

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|-------|--|--|------------------|---------|------------------|
| S1 | 6705 | ((ultra adj fine) nano) adj (particles film films) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/02 13:39 |
| S2 | 22132 | planarizing | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/02 13:38 |
| S3 | 7 | S1 with S2 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/02 14:05 |
| S4 | 4597 | nano adj (particles film films) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/02 13:39 |
| S5 | 0 | S4 with S2 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/02 13:39 |
| S6 | 1 | S4 same S2 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/02 13:39 |
| S7 | 20 | S4 and S2 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/02 13:39 |
| S8 | 8 | S1 same S2 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/02 13:40 |

| | | | | | | |
|-----|---------|--|---|----|-----|------------------|
| S9 | 31 | S1 and S2 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/02 13:42 |
| S10 | 15355 | (particle particles) with (blasting blowing jetting) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/02 13:56 |
| S11 | 4 | S2 with S10 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/02 13:43 |
| S12 | 4 | S2 same S10 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/02 13:43 |
| S13 | 32 | S2 and S10 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/02 13:43 |
| S14 | 28 | S13 not S12 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/02 13:44 |
| S15 | 3029889 | wafer wafers substrate substrates semiconductor semiconductors | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/02 13:44 |
| S16 | 3552 | S10 and S15 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/02 13:45 |

| | | | | | | |
|-----|-------|--------------------------------------|---|----|-----|------------------|
| S17 | 854 | S10 with S15 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/02 13:48 |
| S18 | 10 | S17 and S2 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/02 13:48 |
| S19 | 60 | sandblasting and S2 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/02 13:49 |
| S20 | 59 | S19 and S15 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/02 13:55 |
| S21 | 10484 | S2 with S15 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/02 13:56 |
| S22 | 4 | S12 and S10 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/02 13:56 |
| S23 | 4628 | (particle particles) with (blasting) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/02 13:56 |
| S24 | 26 | S21 and S10 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/02 13:57 |

| | | | | | | |
|-----|----|--|---|----|-----|------------------|
| S25 | 3 | S21 and S23 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/02 13:57 |
| S26 | 4 | ("4993200" "6821906").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/02 14:03 |
| S27 | 15 | (("3100724") or ("4172558") or ("4801411") or ("5120366") or ("5795626") or ("5928719")).PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/08/02 14:05 |